adopting a substrate which is flexible enough to follow up the deformation of the molding resin, it is possible to keep the internal stress between the substrate and the molding resin very low.

IN THE ABSTRACT

Please cancel the Abstract and substitute therefor the Abstract of the Disclosure on the attached separate page.

IN THE CLAIMS

Please cancel claims 1-25 without prejudice or disclaimer and add new claims 26-30 as set forth below.

--26. A method of manufacturing a semiconductor device, comprising the steps of:

providing a flexible writing substrate having a plurality of device areas and a plurality of electrodes formed on each device area;

providing semiconductor chips each having a main surface and a plurality of electrodes formed on the main surface;

mounting the semiconductor chips respectively on the device areas;

connecting electrodes of the semiconductor chips with the electrodes of the flexible wiring substrate on respective device areas by means of conductive members;

sealing the semiconductor chips and the plural device areas by a resin body formed according to a block molding method;

cutting the flexible wiring substrate and the resin body to divide them into respective device areas using a cutting blade,

wherein the cutting step, a rotation axis of the cutting blade is positioned over the back surface of the flexible wiring substrate, and advancing the cutting blade so as to push the flexible wiring substrate against the resin body with a cutting edge thereof.

--27. A method of manufacturing a semiconductor device according to claim 26, in the mounting step, facing a back surface of the semiconductor chip to the flexible wiring substrate, and arranging the semiconductor chip as the electrodes of the flexible wiring substrate is positioned at the outside of corresponding semiconductor chips,

in the connecting step, connecting the electrodes of the semiconductor chips with the electrodes of the flexible

wiring substrate by wire bonding method with a plurality of wires, and

in the sealing step, sealing connecting portions of the wires and the electrodes of the flexible wiring substrate by the resin body.

--28. A method of manufacturing a semiconductor device according to claim 27, in the cutting step, cutting all outlines of device areas with advancing the cutting blade so as to push the flexible wiring substrate against the resin body by a cutting edge thereof.

--29. A method of manufacturing a semiconductor device according to claim 27, wherein the flexible wiring substrate is comprised of a polyimide film.

--30. A method of manufacturing a semiconductor device according to claim 28, wherein the flexible wiring substrate is comprised of a polyimide film.--